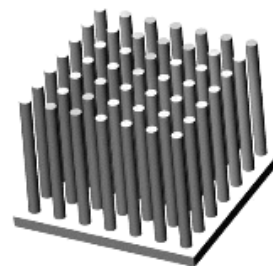


Product- information Type: PB2525/10/SE/SF

Group: Special heatsinks, Finger shaped heatsinks

Heatsinks for Microprocessors (PGA, BGA, IC)

| | |
|------------------------------|----------------|
| Application (Cases): | PGA, BGA, IC |
| Number of semiconductors: | 1 |
| Mounting of semiconductors : | to glue |
| Mounting of heatsinks: | to glue |
| Finish: | black anodized |
| Thermal resistance: | 5.6 K/W |
| Material: | AL 99,5 |



Heatsinks for microprocessors

- Direct mounting with highly thermally conductive self-adhesive foil
- Best possible heat radiation from black anodized surface
- Other dimensions and surface finishes by request
- RthKvalues apply to natural convection (without external ventilation)

Made from pure aluminium (Al 99,5-thermal conductivity 210-236 W/mK)

(Cold forging technology)

- further improved thermal conductivity due to high material density.

